Technical Specification Group RAN
Meeting #5, Kyongju, Korea, 6-8 October 1999

***TSGR#5(99)549***

**Source:** **Siemens, Ericsson, Nokia, NEC, NTT DoCoMo, InterDigital, Italtel**

**Title:** **Text Proposal for TS 25.223**

**Document for:** **Approval**

**Agenda Item:** **6.5**

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Discussion:

TSG RAN #5 received contributions from CWTS regarding the introduction of a low chiprate for TDD, specifically proposing a rate of 1.28 Mchip/s. The already existing TS 25.223 contains the low chiprate in the table of chapter 4, without providing a specific figure.

In the 3GPP ITU contribution we have highlighted the harmonisation potential of the 3GPP TDD and the TD-SCDMA concepts. To underline this position, it is seen as beneficial to recognize the received input, and to modify the TS25.223 accordingly to the following text proposal.

All other intended modifications are subject of further contributions and discussions to be treated in all Working Groups of TSG RAN.

Text proposal:

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# 4 General

In the following, a separation between the data modulation and the spreading modulation has been made. The data modulation is defined in section 5 and the spreading modulation in section 6.

**Table 1: Basic modulation parameters.**

| | | |
|---|---|---|
| Chip rate | same as FDD basic chiprate, 3.84 Mchip/s | Low chiprate: ~~Value is FFS~~ 1.28 Mchip/s |
| Data modulation | QPSK | QPSK |
| Spreading characteristics | Orthogonal Q chips/symbol, where $Q = 2^p$, $0 <= p <= 4$ | Orthogonal Q chips/symbol, where $Q = 2^p$, $0 <= p <= 4$ |